Amendments to the Claims:

This listing of the Claims will replace all prior versions and listings of the claims in this patent application.

Listing of Claims:

1. (currently amended) A ~~circuitry~~ circuit component comprising:
   a semiconductor substrate;
   a metallization structure over said semiconductor substrate;
   a passivation layer over said metallization structure, wherein an opening in said passivation layer exposes a top surface of said metallization structure; and
   a patterned circuit layer connected to said top surface through said opening, wherein said patterned circuit layer comprises a first portion used to have a bump formed thereover and a second portion comprising a gold layer, wherein said gold layer is used to be in contact with a testing probe, and wherein said first portion is connected to said second portion. ~~used to be tested thereto.~~

2. (canceled)

3. (currently amended) The ~~circuitry~~ circuit component of Claim 1, wherein ~~said patterned circuit layer comprises a~~ said gold layer has ~~having~~ a thickness of greater than 1 micron.

4. (canceled)

5. (currently amended) The ~~circuitry~~ circuit component of Claim 1, wherein said patterned circuit layer comprises a nickel layer under said gold layer.

6. (currently amended) The ~~circuitry~~ circuit component of Claim 1, wherein said patterned circuit layer comprises a copper layer under said gold layer. ~~and a gold layer, said gold layer being over said copper layer.~~

7. (currently amended) The ~~circuitry~~ circuit component of Claim 1[[6]], wherein said patterned circuit layer further comprises a copper layer and a nickel layer over said copper layer, and wherein said gold layer is over said nickel layer. ~~between said copper layer and said gold layer.~~

8. (currently amended) The ~~circuitry~~ circuit component of Claim 1 further comprising a polymer layer between ~~over~~ said passivation layer~~, wherein~~ and said patterned circuit layer ~~is over said polymer layer~~.

9. (currently amended) The ~~circuitry~~ circuit component of Claim 8, wherein said polymer layer comprises polyimide.

10. (currently amended) The ~~circuitry~~ circuit component of Claim 1 further comprising a polymer layer on said patterned circuit layer, multiple openings ~~an opening~~ in said polymer layer exposing said first and second portions. ~~portion.~~

11. (currently amended) The ~~circuitry~~ circuit component of Claim 10, wherein said polymer layer comprises polyimide.

Claim 12 (canceled)

13. (currently amended) The ~~circuitry~~ circuit component of Claim 1, wherein said patterned circuit layer comprising a metal line ~~trace~~ connecting said first and second

portions.

Claim 14 (canceled)

15. (currently amended) The ~~circuitry~~ circuit component of Claim 1, wherein said passivation layer comprises a topmost nitride layer of said circuit ~~electronic~~ component.

16. (currently amended) The ~~circuitry~~ circuit component of Claim 1, wherein said passivation layer has a thickness of greater than 0.35 μm.

17. (currently amended) The ~~circuitry~~ circuit component of Claim 1 further comprising a bump on said first portion.

18. (currently amended) The ~~circuitry~~ circuit component of Claim 17 further comprising a nickel layer between said bump and said first portion.

19. (currently amended) The ~~circuitry~~ circuit component of Claim 17, wherein said bump comprises solder.

20. (currently amended) The ~~circuitry~~ circuit component of Claim 17 further comprising a copper layer between said bump and said first portion.

21. (currently amended) The ~~circuitry~~ circuit component of Claim 17, wherein said bump comprises a lead-free alloy.

Claim 22 (canceled)

23. (withdrawn and currently amended) The ~~circuitry~~ circuit component of Claim 1,

wherein said patterned circuit layer comprises a third portion used to be wirebonded thereto.

24. (withdrawn and currently amended) The ~~circuitry~~ circuit component of Claim 23, wherein said patterned circuit layer comprises a metal trace connecting said second and third portions.

25. (currently amended) The ~~circuitry~~ circuit component of Claim 1, wherein a ~~the~~ pitch between said first and second portions is less than 300 μm.

26. (currently amended) The ~~circuitry~~ circuit component of Claim 1, wherein a ~~the~~ pitch between said first and second portions is less than 1 millimeter.

27. (currently amended) A ~~circuitry~~ circuit component comprising:

a semiconductor substrate;

a metallization structure over said semiconductor substrate;

a passivation layer over said metallization structure, wherein an opening in said passivation layer exposes a top surface of said metallization structure; and

a patterned circuit layer connected to said top surface through said opening, wherein said patterned circuit layer comprises ~~a first metal layer and a second metal layer over said first metal layer, wherein said second metal layer has~~ a first portion used to have a bump formed thereover and a second portion comprising a copper layer, wherein said copper layer is used to be wirebonded thereover. ~~thereto.~~

28. (currently amended) The ~~circuitry~~ circuit component of Claim 27, wherein said patterned circuit layer further comprises a titanium-containing layer under said copper layer. ~~second metal layer comprises gold.~~

29. (currently amended) The ~~circuitry~~ circuit component of Claim 27, wherein said patterned circuit layer further comprises a chromium-containing layer under said copper layer. ~~second metal layer comprises copper.~~

30. (currently amended) The ~~circuitry~~ circuit component of Claim 27 further comprising a polymer layer between ~~over~~ said passivation layer~~, wherein~~ and said patterned circuit layer ~~is over said polymer layer~~.

31. (currently amended) The ~~circuitry~~ circuit component of Claim 30, wherein said polymer layer comprises polyimide.

32. (currently amended) The ~~circuitry~~ circuit component of Claim 27 comprising a polymer layer on said patterned circuit layer, multiple openings ~~an opening~~ in said polymer layer exposing said first and second portions. ~~portion.~~

33. (currently amended) The ~~circuitry~~ circuit component of Claim 32, wherein said polymer layer comprises polyimide.

34. (currently amended) The ~~circuitry~~ circuit component of Claim 27, wherein said patterned circuit layer comprises a metal line ~~trace~~ connecting said first and second portions.

35. (withdrawn and currently amended) The ~~circuitry~~ circuit component of Claim 27, wherein said patterned circuit layer comprises a third portion used to be in contact with a testing probe. ~~tested thereto.~~

Claim 36 (canceled)

37. (withdrawn and currently amended) The ~~circuitry~~ circuit component of Claim 35, wherein said patterned circuit layer comprises a metal trace connecting said first and third portions. ~~the pitch between said first and second portions is less than 300 μm.~~

38. (currently amended) The ~~circuitry~~ circuit component of Claim 27, wherein said passivation layer has a thickness of greater than 0.35 μm.

39. (currently amended) The ~~circuitry~~ circuit component of Claim 27, wherein said passivation layer comprises a topmost nitride layer of said circuit ~~electronic~~ component.

40. (currently amended) The ~~circuitry~~ circuit component of Claim 27 further comprising a bump over said first portion.

41. (currently amended) The ~~circuitry~~ circuit component of Claim 40, wherein said bump comprises solder.

42. (currently amended) The ~~circuitry~~ circuit component of Claim 40 further comprising a nickel ~~copper~~ layer between said bump and said first portion.

43. (currently amended) The ~~circuitry~~ circuit component of Claim 40, wherein said bump comprises a lead-free alloy.

44. (currently amended) The ~~circuitry~~ circuit component of Claim 27 further comprising a wirebonded wire bonded over said second portion.

Claim 45 (canceled)

46. (withdrawn and currently amended) A ~~circuitry~~ circuit component comprising:

a semiconductor substrate;

a metallization structure over said semiconductor substrate;

a passivation layer over said ~~over said~~ metallization structure, wherein an opening in said passivation layer exposes a top surface of said metallization structure; and

a patterned circuit layer connected to said top surface through said opening, wherein said patterned circuit layer comprises a first portion used to be wirebonded thereto and a second portion used to be in contact with a testing probe. ~~tested thereto.~~

47. (withdrawn and currently amended) The ~~circuitry~~ circuit component of Claim 46, wherein said patterned circuit layer comprises gold.

48. (withdrawn and currently amended) The ~~circuitry~~ circuit component of Claim 46, wherein said patterned circuit layer comprises a gold layer having a thickness of greater than 1 micron.

49. (withdrawn and currently amended) The ~~circuitry~~ circuit component of Claim 46, wherein said patterned circuit layer comprises copper.

50. (withdrawn and currently amended) The ~~circuitry~~ circuit component of Claim 46, wherein said patterned circuit layer comprises nickel.

51. (new) The circuit component of Claim 27, wherein said second portion further comprises a nickel layer over said copper layer, and wherein said nickel layer is used to be said wirebonded thereover.

52. (new) The circuit component of Claim 27, wherein said second portion further

comprises a gold layer over said copper layer, and wherein said gold layer is used to be said wirebonded thereon.

5